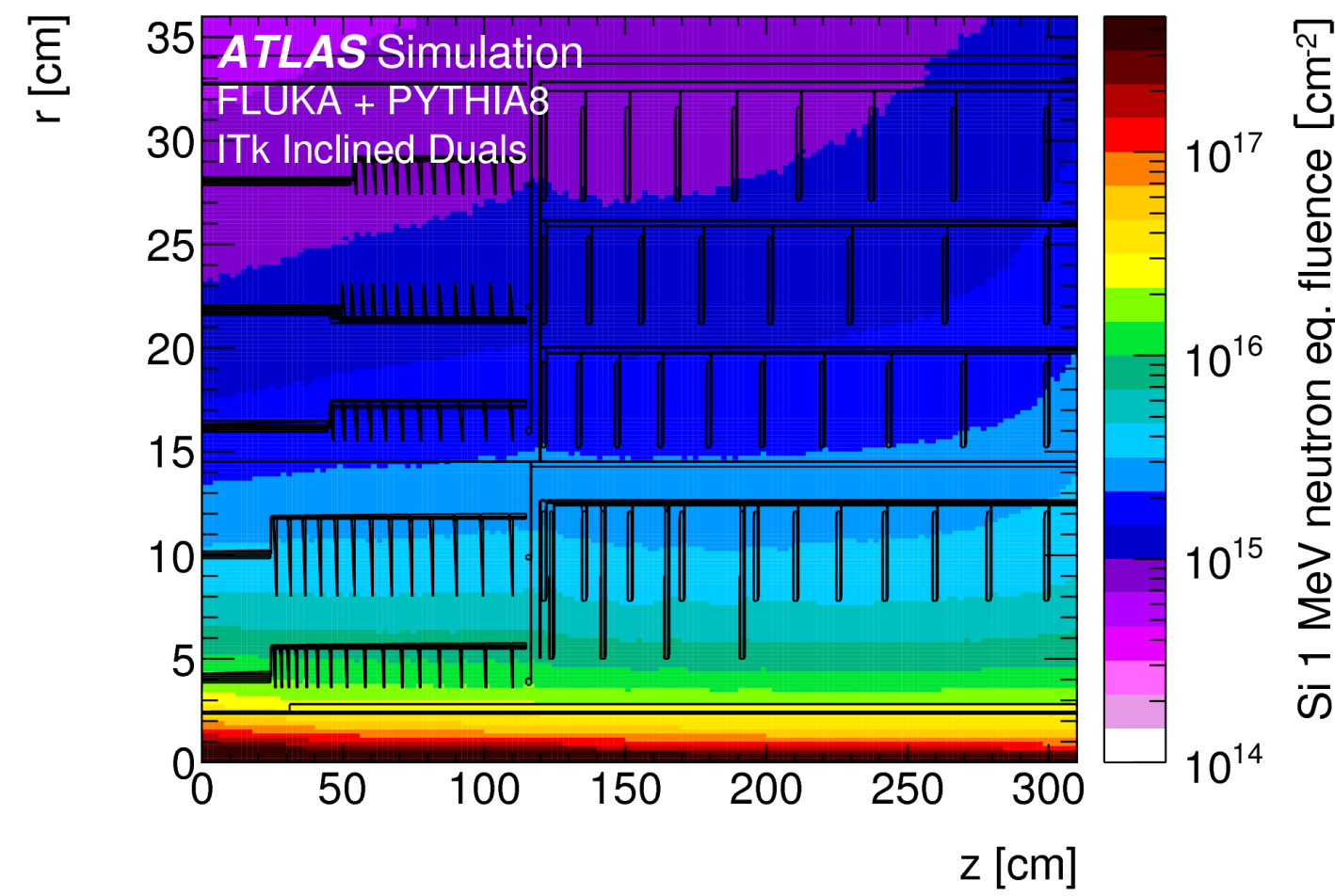


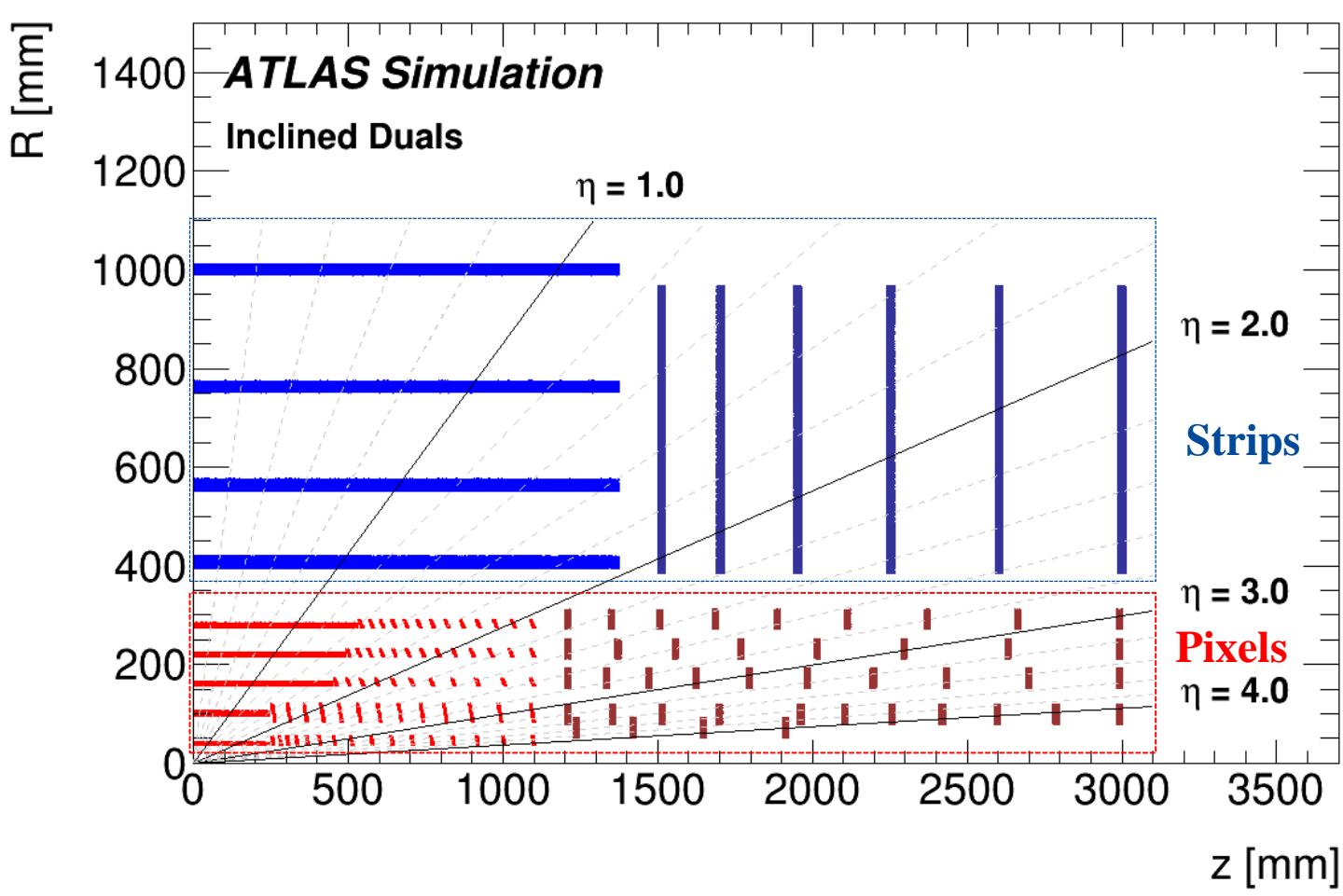
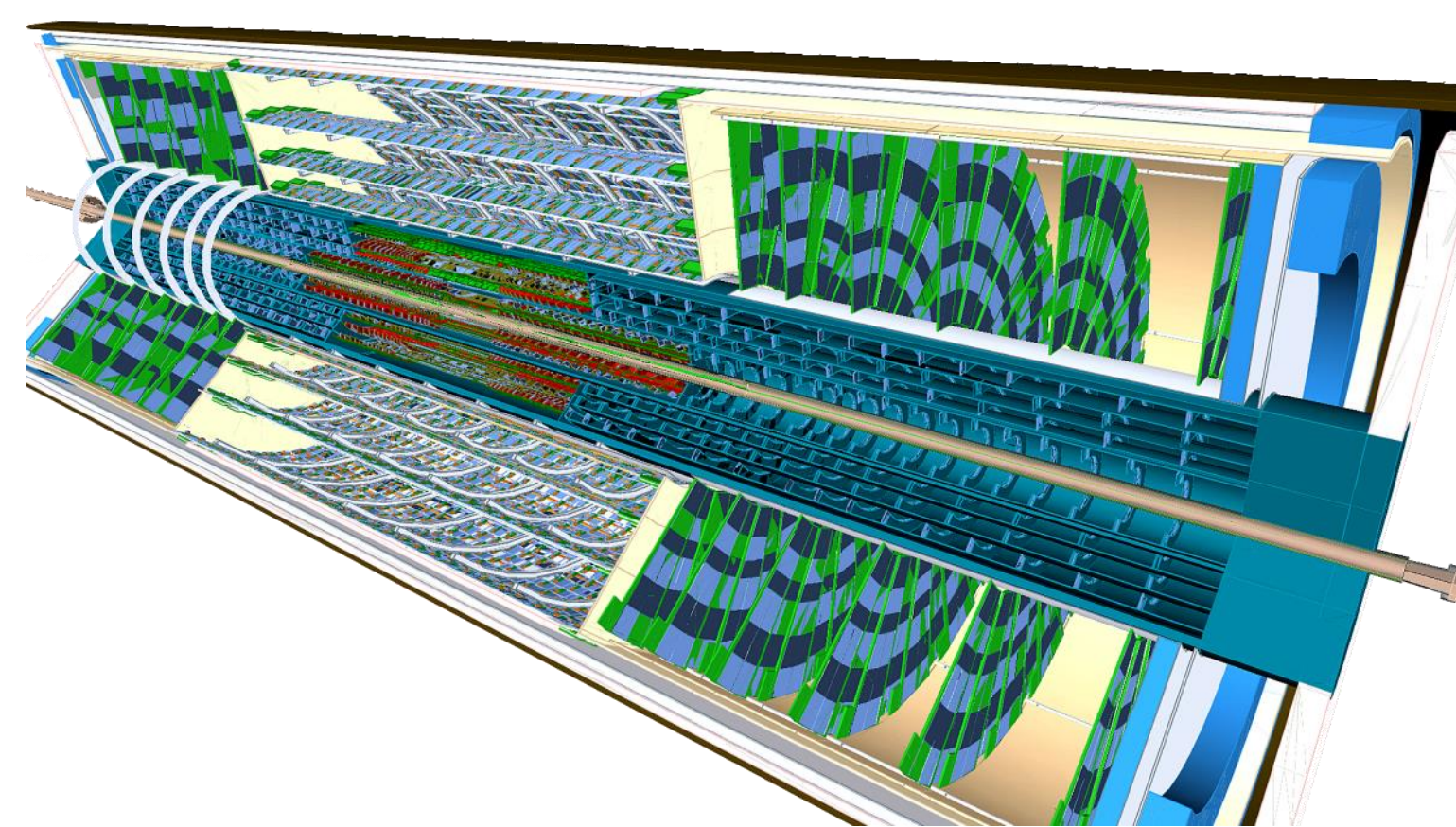
## ATLAS Inner Tracker for HL-LHC (ITk)

At the HL-LHC the ITk detector will face:

- Radiation Damage**
  - HL-LHC should deliver  $\sim 4000 \text{ fb}^{-1}$  (current inner detector for IBL  $\sim 850 \text{ fb}^{-1}$ )
  - New sensor design requires **increased radiation hardness**
- Pileup  $\sim 200$** 
  - Keep current inner detector occupancy **granularity increased by  $\sim 10\times$**



- All silicon design
- Higher granularity
- Minimum material
- $\eta$  coverage increased to 4 (currently  $\sim 2.5$ )
- $\text{CO}_2$  cooling



### ITk Pixel Detector:

- 5 barrel layers: short barrel + inclined modules ( $|\eta| < 1.4$ ) + endcap rings ( $|\eta| < 4$ )

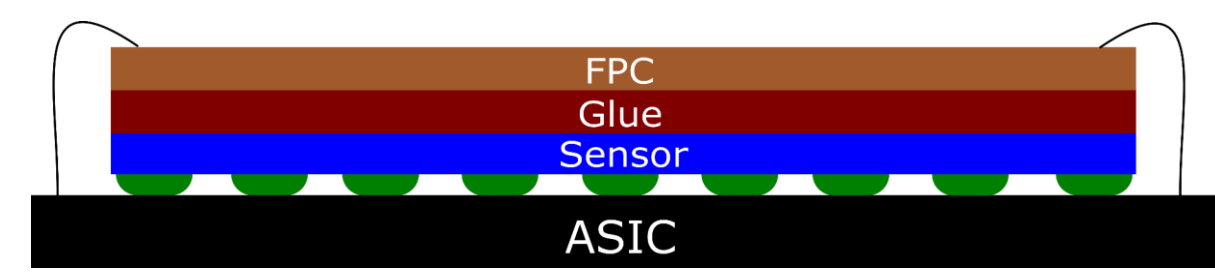
### ITk Strip Detector:

- 4 barrel layers + 2x6 endcap wheels ( $|\eta| < 2.7$ )

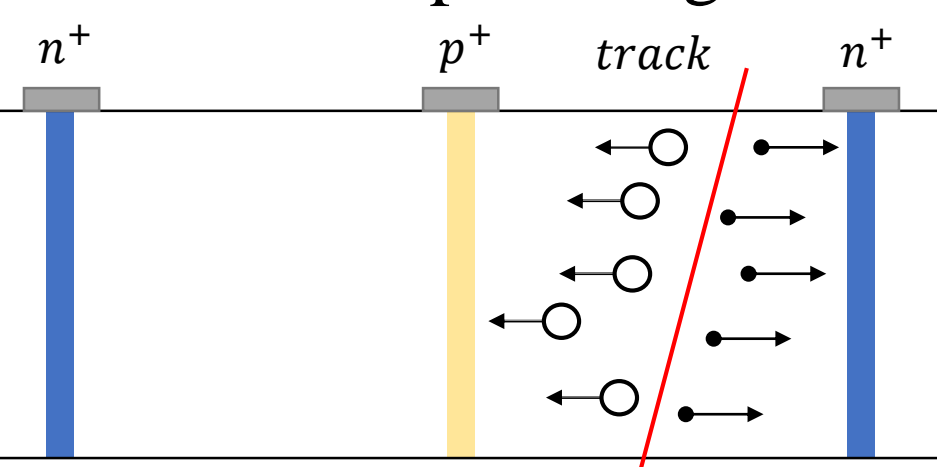
## ITk Pixel Detector

Pixel Module development:

- Si n-in-p technology, small pixel size
- FE chip: Gbps readout capability
- Flip-chip using bump bonding
- Serial powering scheme

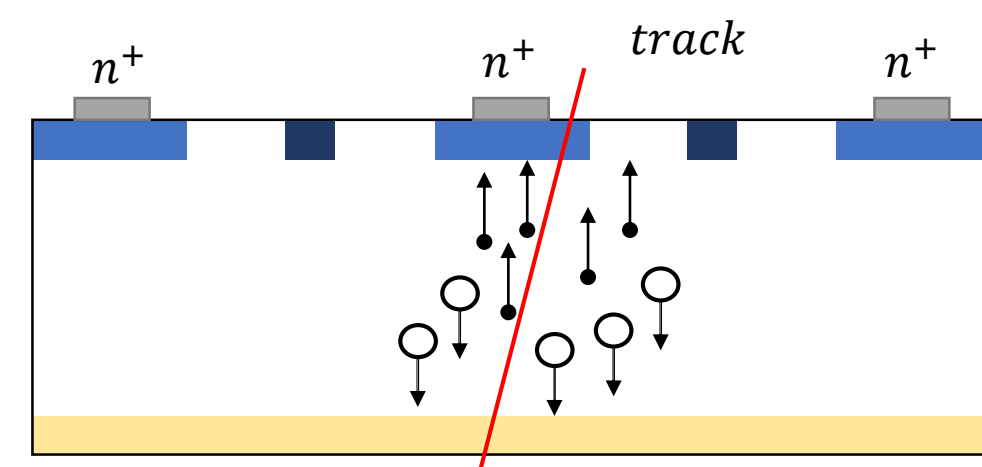


- Sequence development on going:
  - Attachment, wire bonding, encapsulation



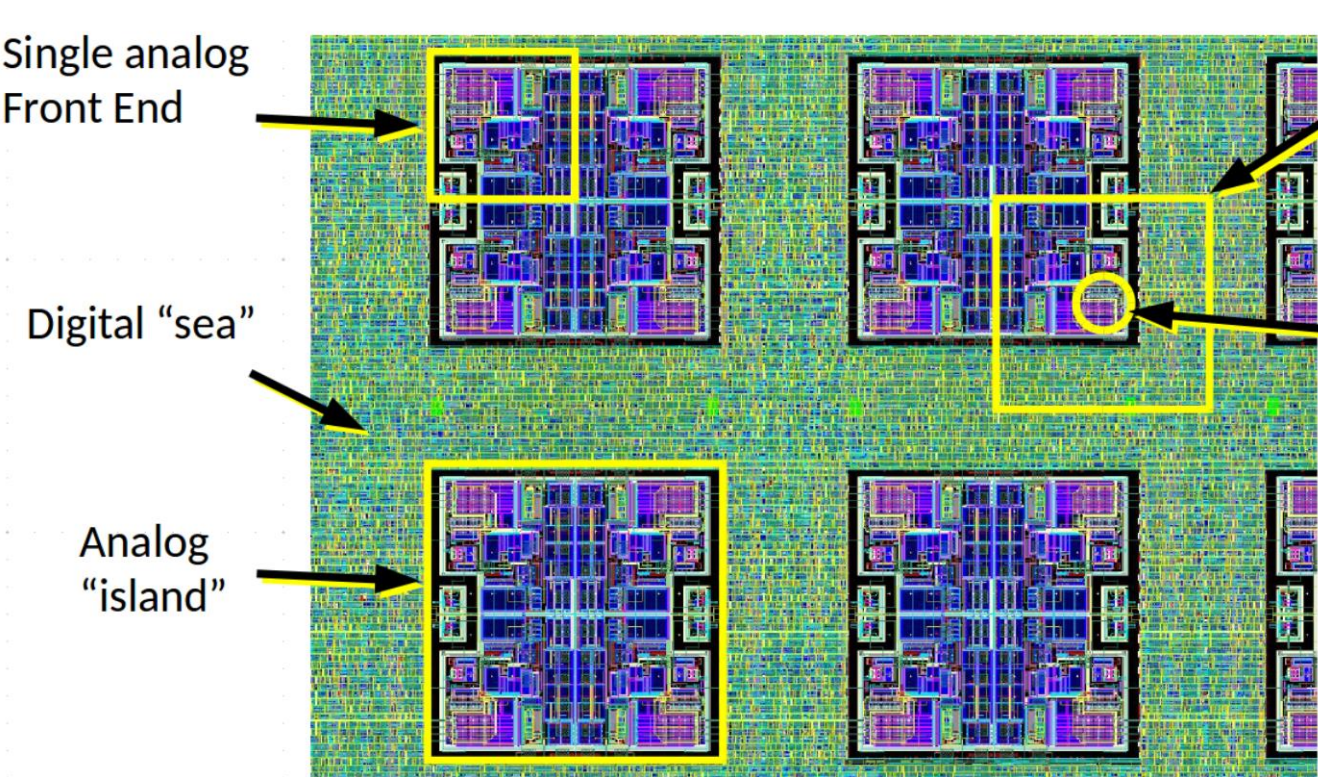
Pixel size:  $50 \times 50 \mu\text{m}^2$  or  $25 \times 100 \mu\text{m}^2$

Considering CMOS for outermost layer



- Planar n-in-p type other layers
- Thinned to  $\sim 150 \mu\text{m}$

## ASIC rad hard 65nm CMOS: Joint ATLAS & CMS project within RD53 collaboration

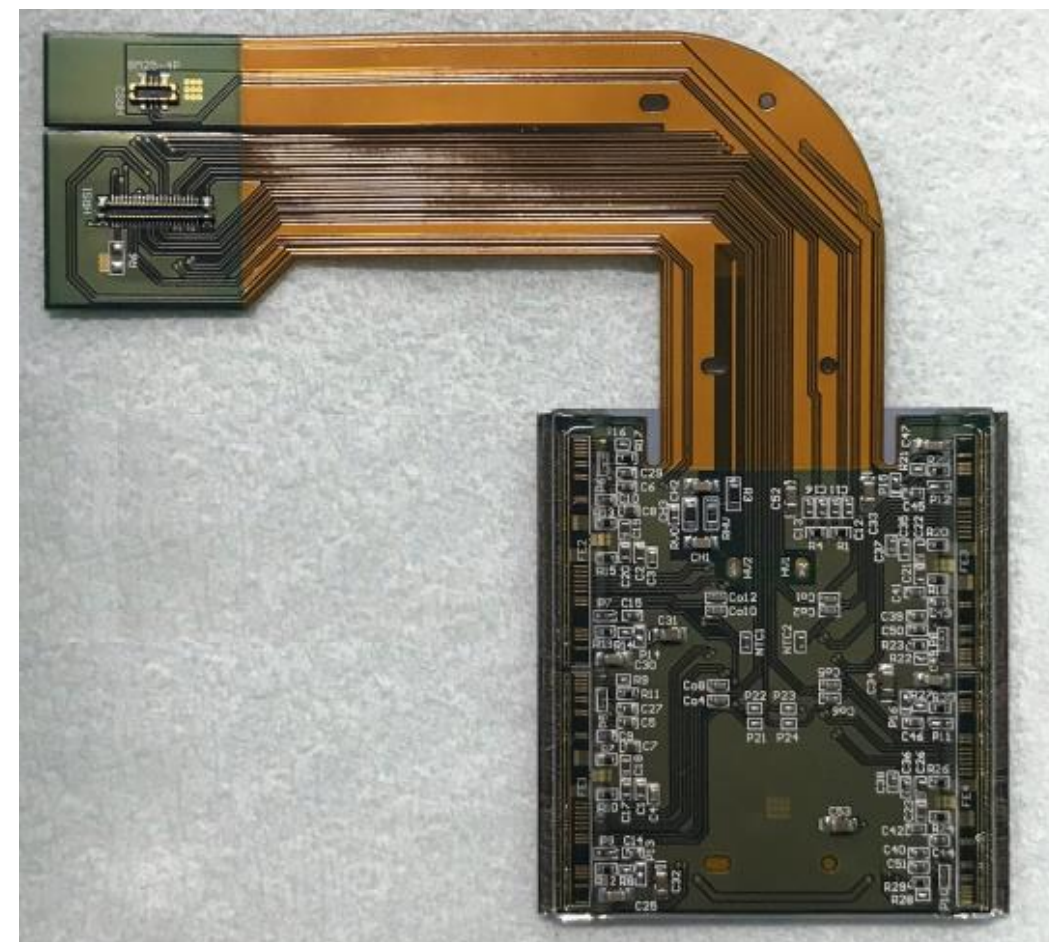


Example of square pixel on sensor above

Bump bond location

- Data rate  $\sim 1.28 \text{ Gbps}$
- Noise rate ( $< 10^{-6}$ ,  $600 e^-$ )
- RD53A first prototype of the final readout ASIC

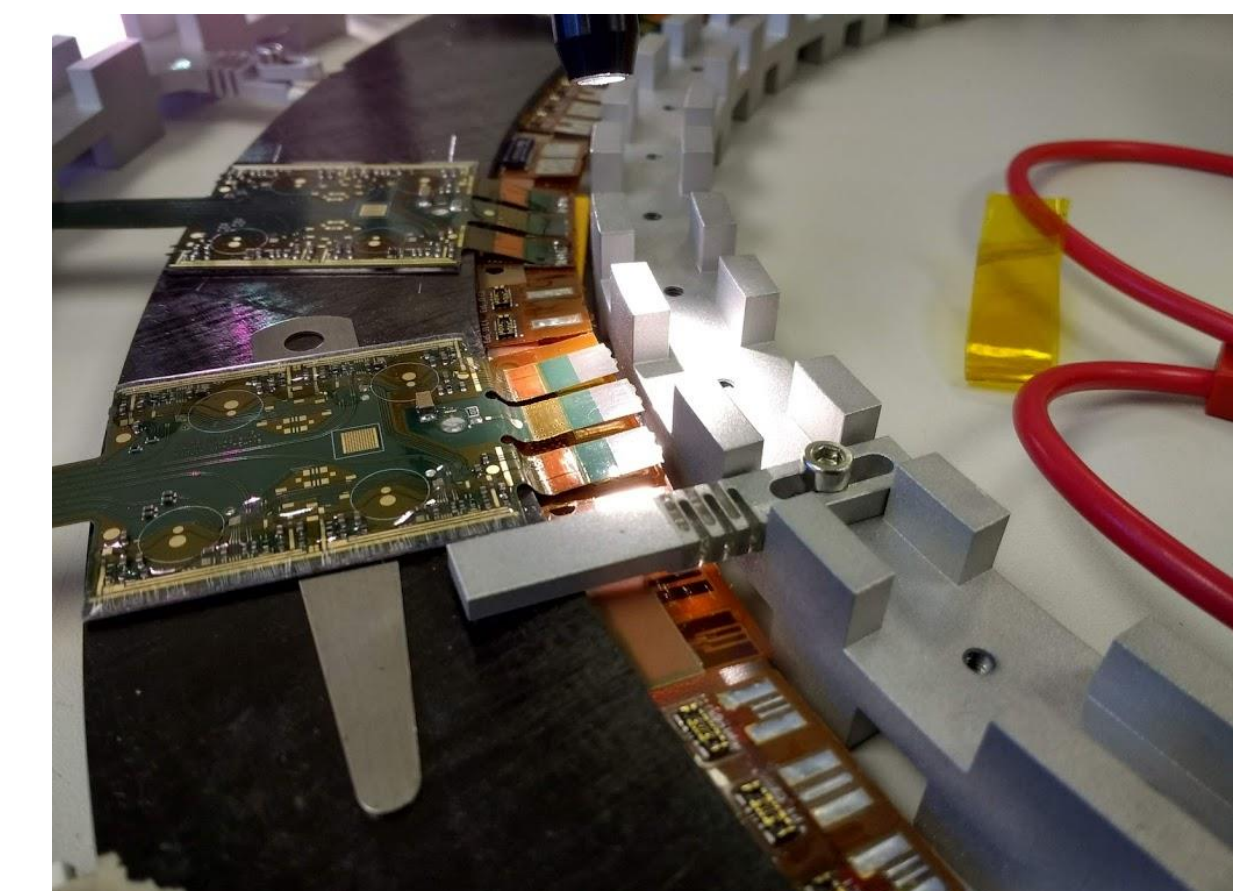
<http://rd53.web.cern.ch/rd53/>



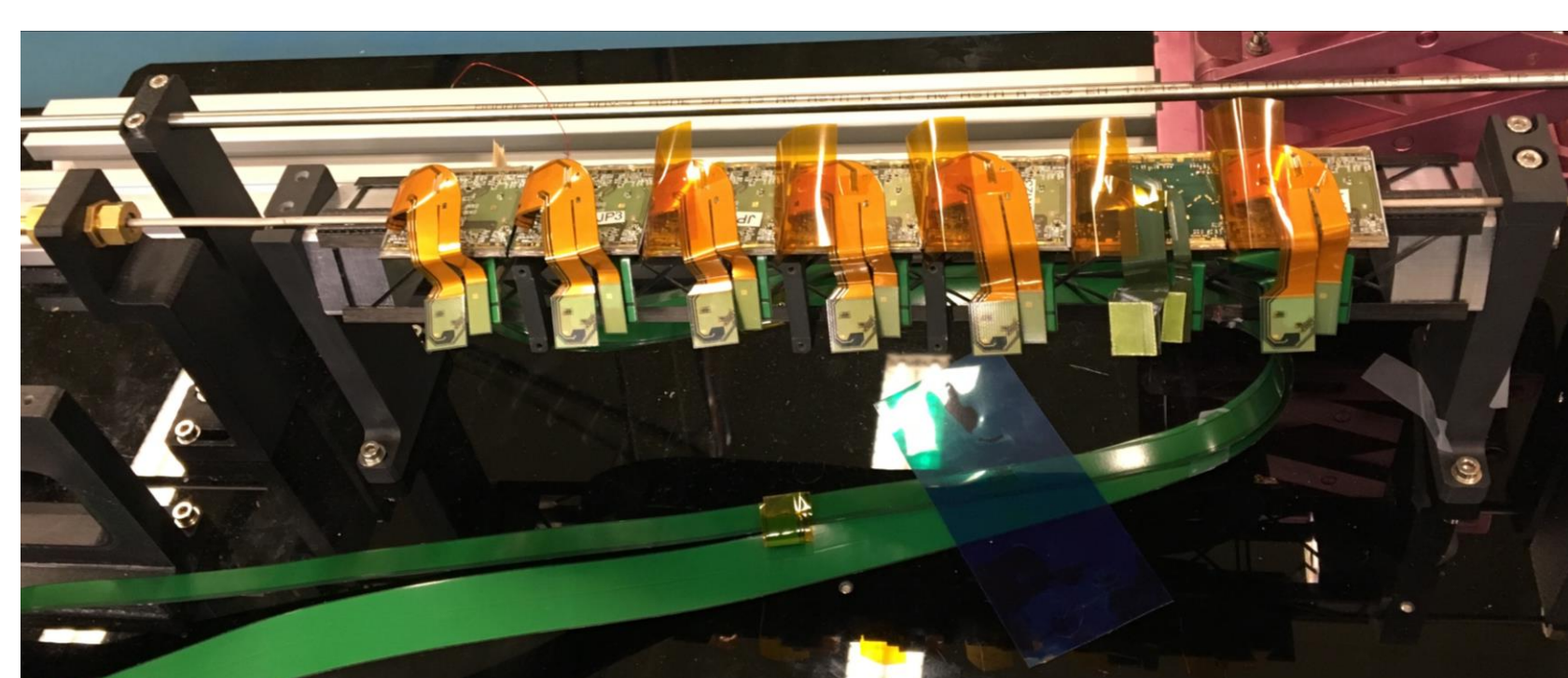
Quad barrel module



Quad module for outer endcaps



Loading tests with modules on Endcap ring local support

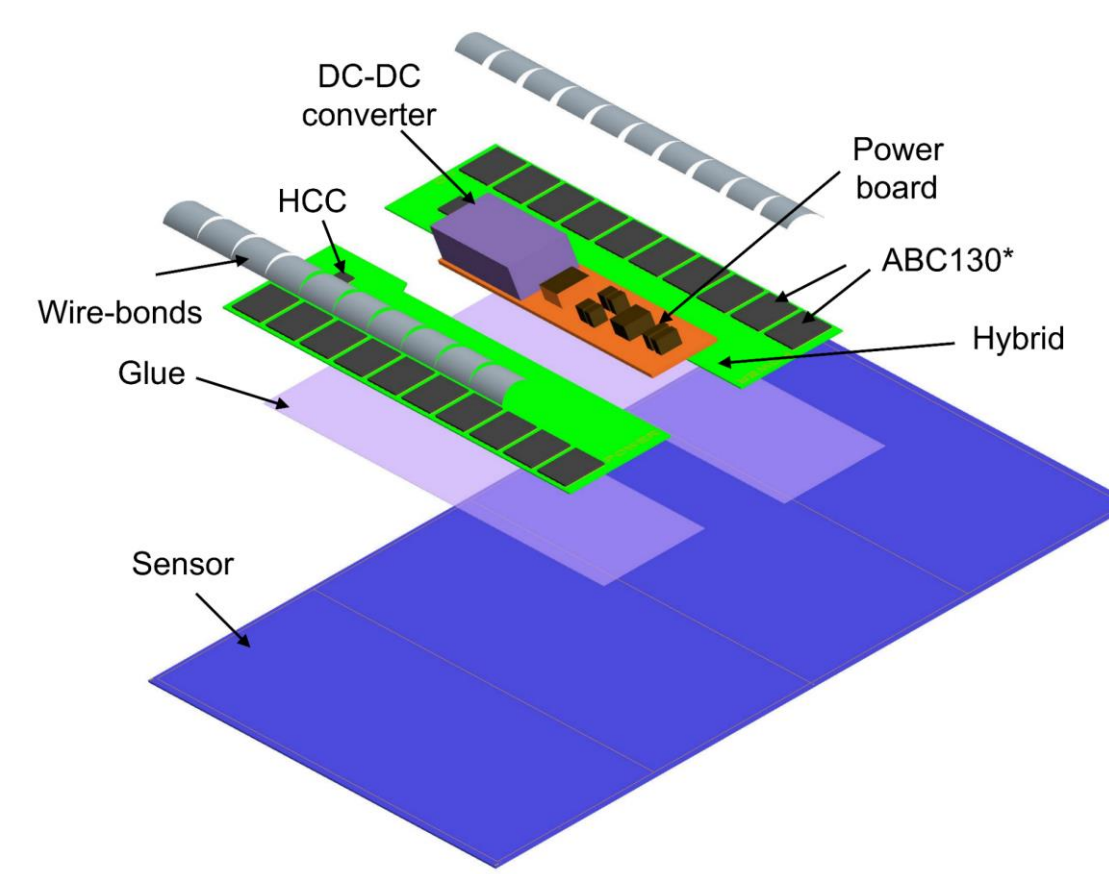


7 loaded FE-14 quad modules on outer barrel stave prototype

## ITk Strip Detector

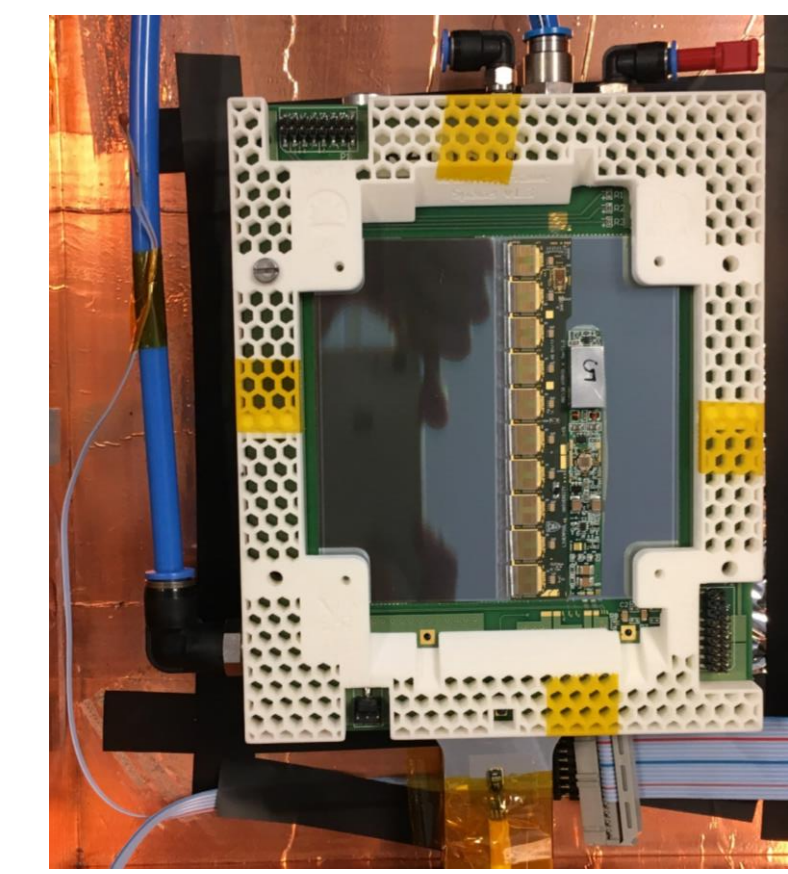
### ITk Strip Module:

- One sensor
  - Planar Si n-in-p
- Low mass PCBs (hybrids)
- Power board with DC-DC
- ASICs ABC 130 nm CMOS



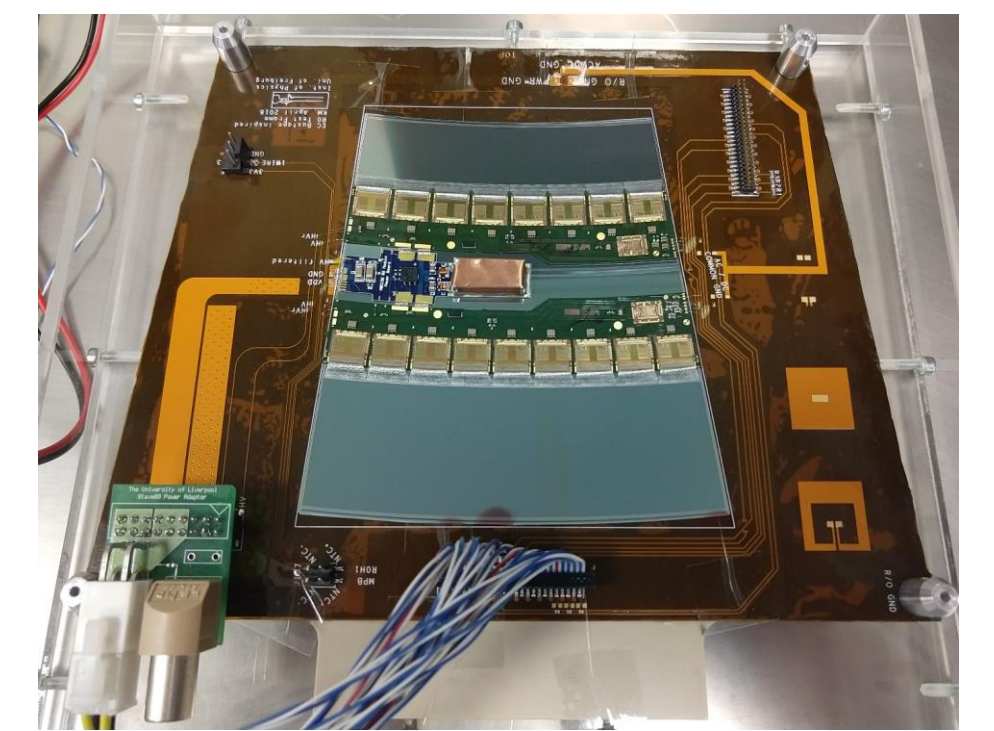
### Barrel Module:

- Rectangular geometry
  - Strip length 2.4 – 4.8 cm
  - Pitch 75.5  $\mu\text{m}$
  - Stereo angle 52 mrad
- 2 different modules



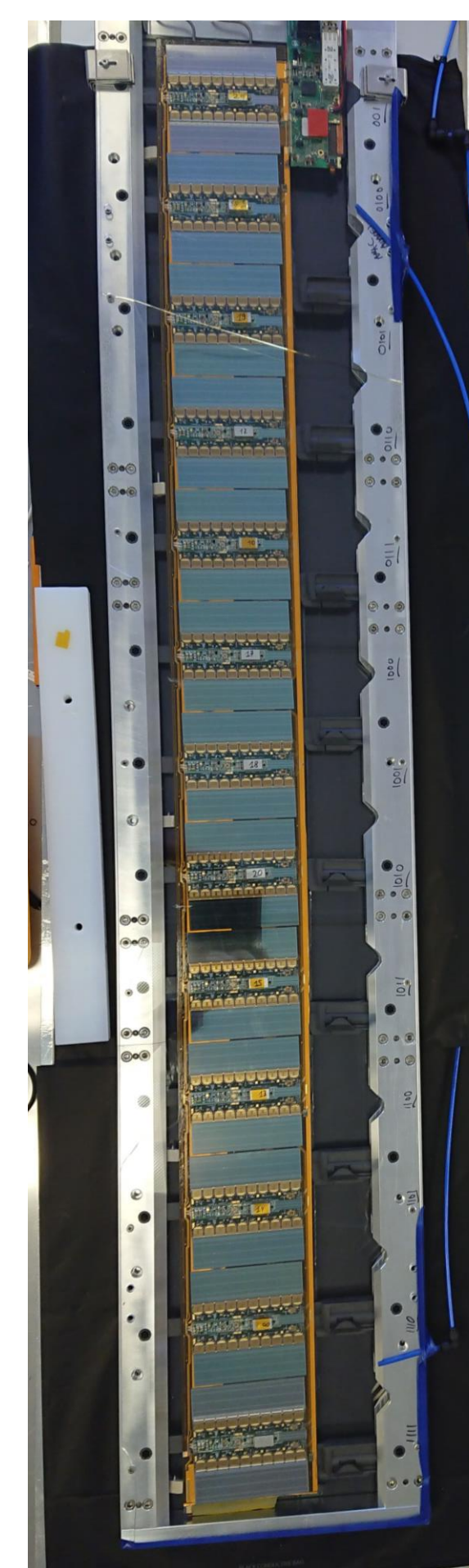
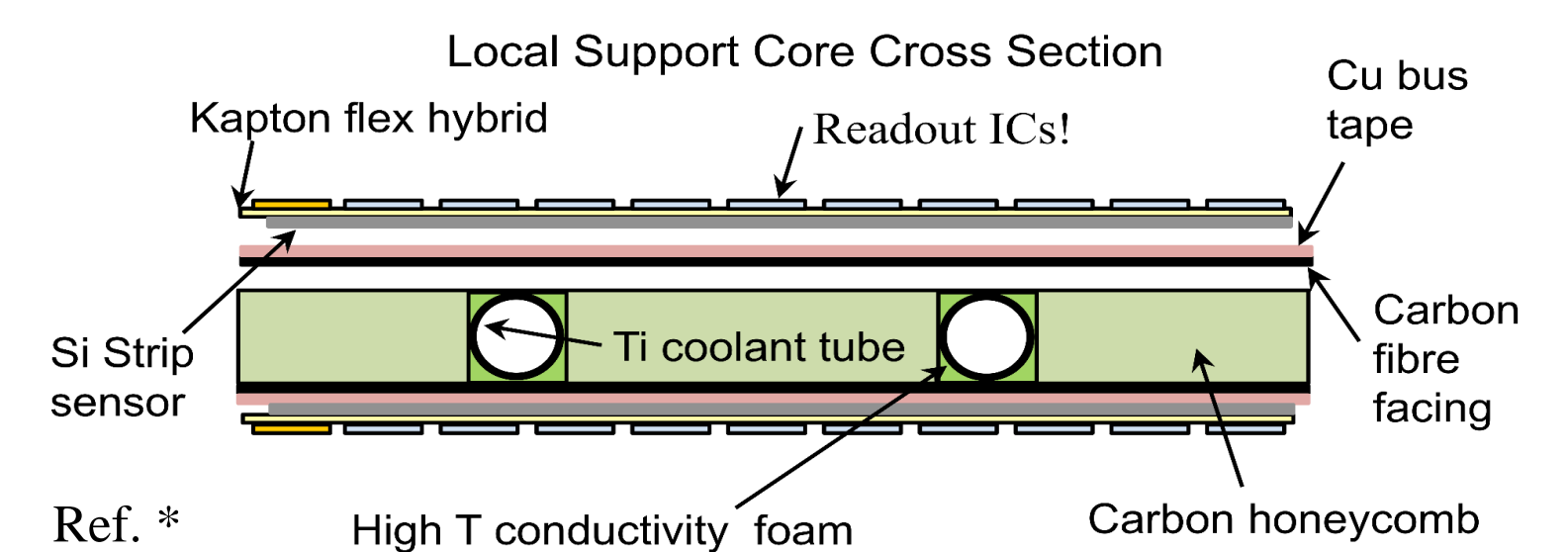
### Endcap Module:

- Radial geometry
  - Strip length 1.9 – 6 cm
  - Pitch 69.9 – 80.7  $\mu\text{m}$
  - Stereo angle 40 mrad
- 6 different modules



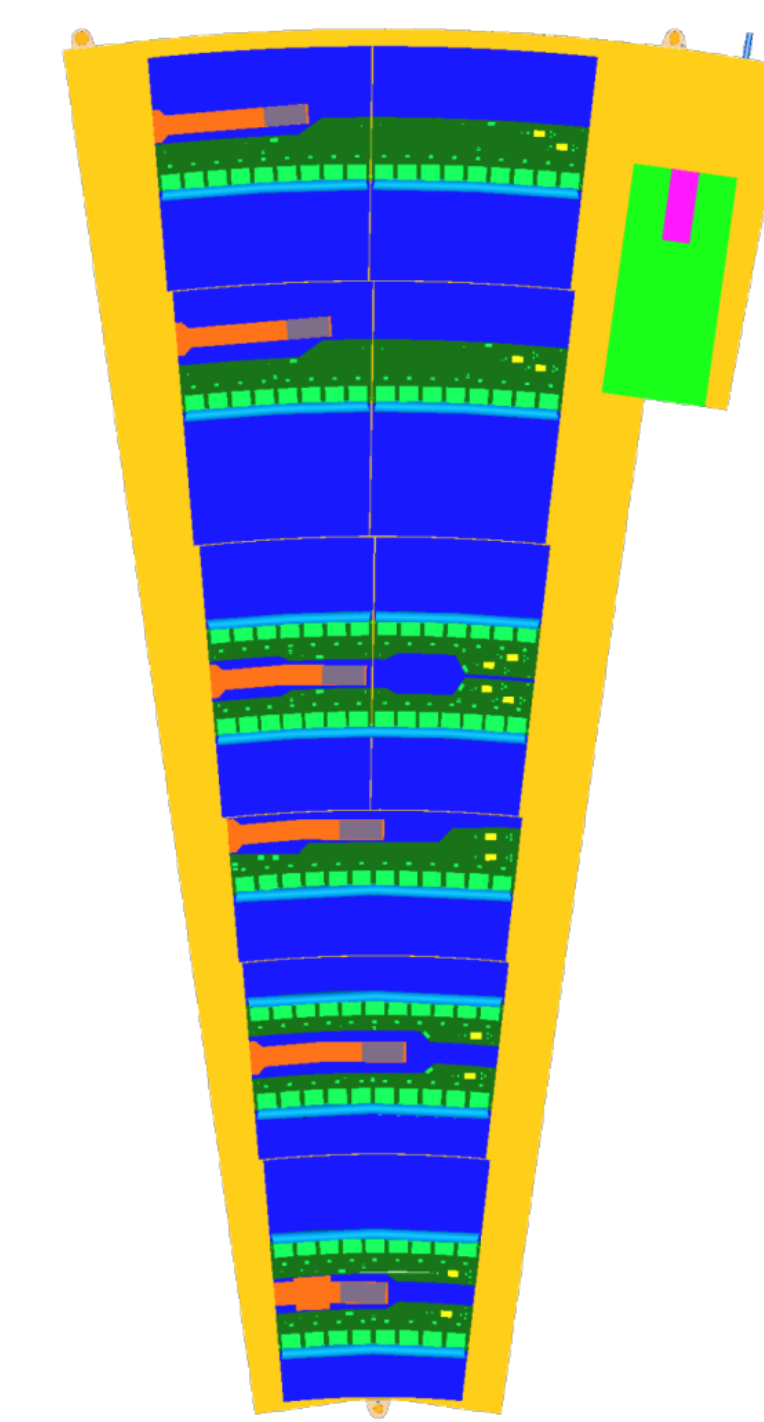
### Local Support:

- Mechanical stability requirement: Barrel and endcap  $z$ ,  $R$  ( $20 \mu\text{m}$ ),  $\phi$  ( $2 \mu\text{m}$ )
- Titanium cooling pipes
- Electrical services



Barrel staves

### Basic building units



R5

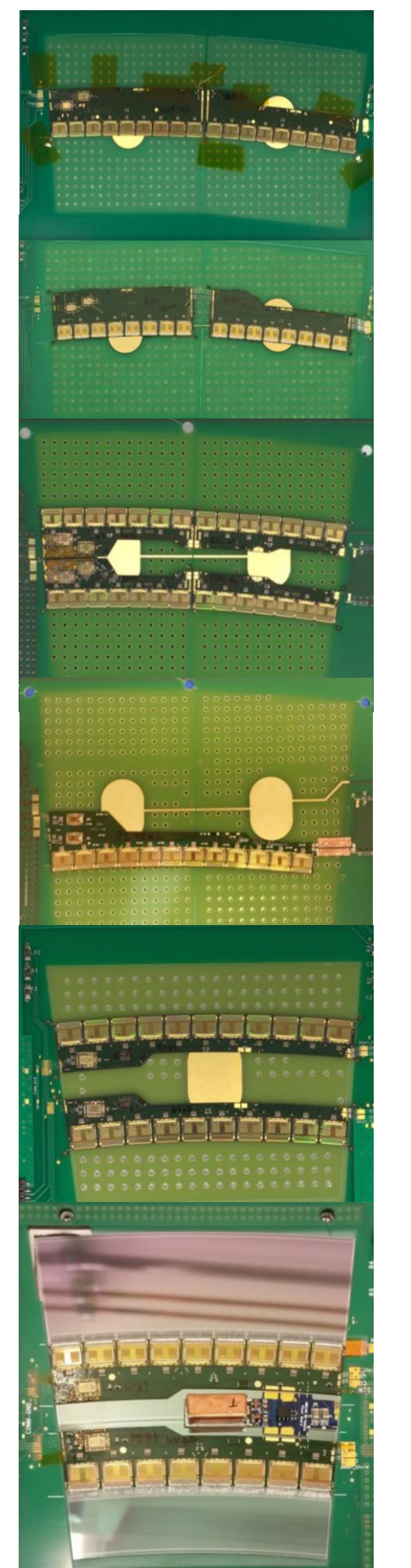
R4

R3

R2

R1

R0



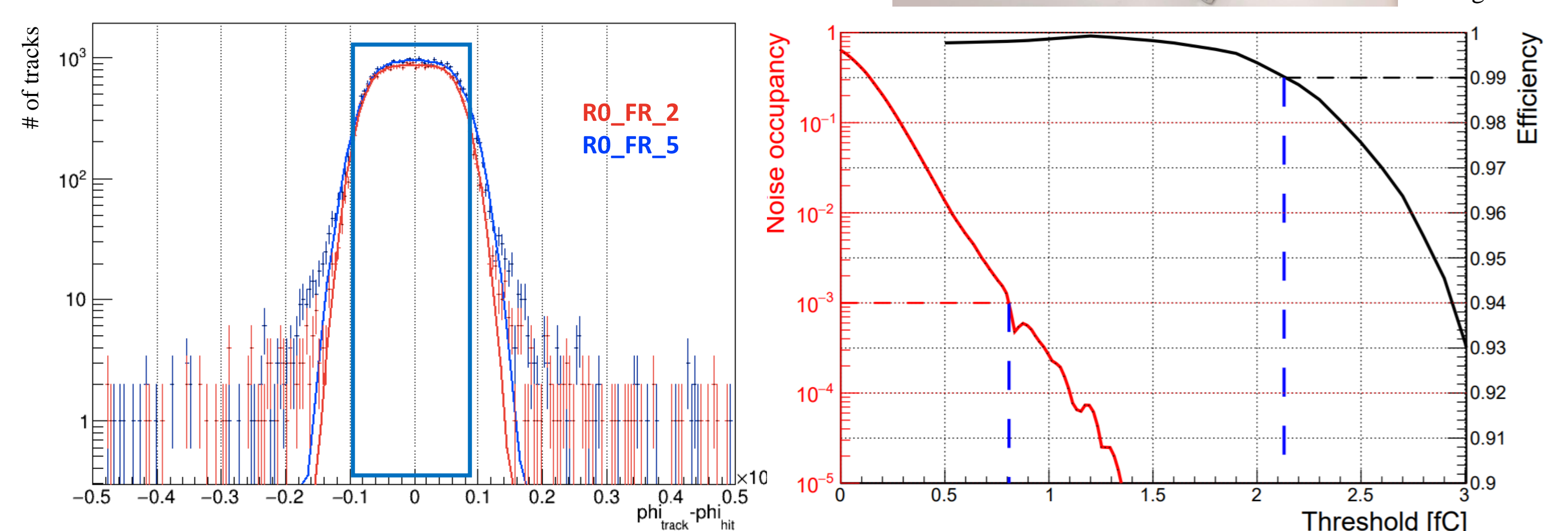
Endcap petals

## Double-Sided R0 strip module

- Single-sided modules on both sides of a core
- Unirradiated sensors
- Petalet core including coolant tubes
- Readout independently from both sides, using a Nexys board
- Successfully tested in:
  - Freiburg clean room
  - Beam Test at DESY



DS R0 module facing a mirror



Residual distributions of hits with respect to tracks for either side of the double-side with blue box indicating strip pitch (left). Noise occupancy and efficiency as a function of applied threshold in fC (right). Defining operation requirements as efficiency  $> 99\%$  and noise occupancy  $< 10^{-3}$ . The module can be operated using a threshold between 0.8 – 2.1 fC